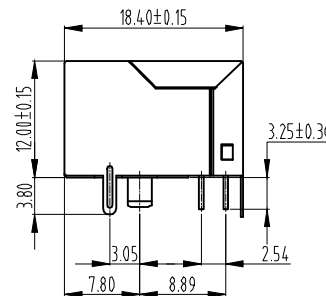
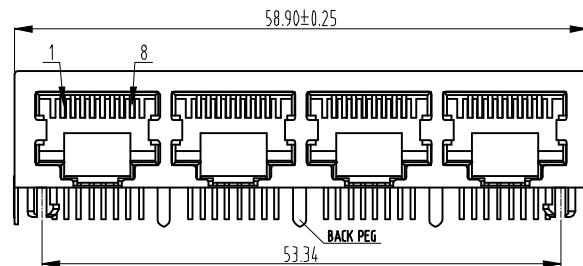


HSF



NOTES:

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE $t=0.3\text{mm}$
3. PLATING: SELECTING GOLD PLATING $1\mu\sim 50\mu$ OVER NICKEL IN CONTACT AREA. 150μ TIN PLATING OVER NICKEL IN SOLDER AREA
4. SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE ELECTRICAL
1. VOLTAGE RATING: 125VAC RMS
2. CURRENT RATING: 1.5AMP
3. CONTACT RESISTANCE: 30MILLIOHMS MAX
4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTION PRB-SOLDER: 1 LB MIN REVISIONAL
1. STORAGE: -40°C TO 85°C
2. OPERATION: 0°C TO 70°C

Order code:

ATRJ5623 - 10P - 8C - X - D - C - A

① ② ③ ④ ⑤ ⑥ ⑦

① SERIES NO:

② NUMBER OF POSITIONS (10P, 8P, 6P, 4P)

③ NUMBER OF CONTACTS (10C, 8C, 6C, 4C)

④ Contact Plating

G0: Gold flash
G1: 3U" Gold
G2: 5U" Gold
G3: 10U" Gold
G4: 15U" Gold
G5: 30U" Gold
SN: Tin

⑤ Shield

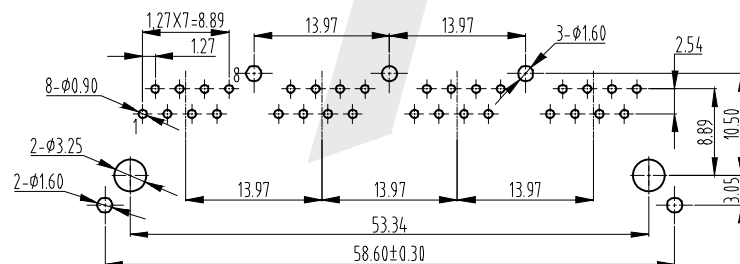
A: W/O Shield
B: Half Shield
C: Shield W/Eml
D: Shield W/O Eml

⑥ Ports

A: 1X1P
B: 1X2P
C: 1X4P
D: 1X5P
E: 1X6P
F: 1X8P

⑦ PCB layout style:

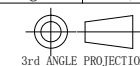
A: TYPE 1 front legs 3.05
B: TYPE 1 front legs 3.68
C: TYPE 1 front legs 4.57
D: TYPE 2 Back legs 3.05
E: TYPE 2 Back legs 3.68
F: TYPE 2 Back legs 4.57



PCB LAYOUT/TOP VIEW

Unless Otherwise specified tolerance
X. ± 0.35 X.XX: ± 0.20
X.X: ± 0.25 X.XXX: ± 0.15

SCALE: As Shown UNIT: mm
DRAW Wu Feng Rong DATE 22/03/2018
CHECK BobYang DATE 22/03/2018



ANTENK ELECTRONICS CO., LTD
Http://www.antenk.com
E-mail: sales@antenk.com

TITLE:

RJ45 Jack side entry, Full shielded

DRAWING NO:

ATRJ5623-10P8C-X-D-C-A

PRODUCT NO:

ATRJ5623-10P8C-X-D-C-A

REV

DESCRIPTION

DATE

1

2

3

4

5

6

7

8